

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	100932	interconnect\$3 with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:18
L8	1960	L7 and (seed seeding) with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:18
L9	1526	L8 and (metal metal\$5) with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:18
L10	469	9 and (heat\$3 anneal\$3 thermal\$5) with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:18
L11	105	10 and (heat\$3 anneal\$3 thermal\$5) near5 first	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:19
L12	63	11 and (heat\$3 anneal\$3 thermal\$5) near5 second	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:19
L13	32	12 and ('ecp' electro adj chemical adj plating electrochemical plating) with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:20
L14	23	13 and ('ecp' electro adj chemical adj plating electrochemical adj plating electroplating)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:21
L15	43	12 and ('ecp' electro adj chemical adj plating electrochemical adj plating electroplating)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:21
S29	100932	interconnect\$3 with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 08:19

S30	1960	S29 and (seed seeding) with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 08:19
S31	1526	S30 and (metal metal\$5) with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:18
S32	469	S31 and (heat\$3 anneal\$3 thermal\$5) with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:18
S33	1006	S31 and (barrier) with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 08:22
S34	275	S32 and (barrier) with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 08:22
S35	129	S34 and ('ecp' electro adj chemical adj plating electrochemical plating) with (damascence dual adj damascence trench via groove hole)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/22 13:19

©-å©; 6-23-2005"

@PJL SET JOBATTR="JobAcct1=DLe5"

@PJL SET JOBATTR="JobAcct2=WS074"